Title: Qualification of TI Chengdu A/T (CDAT) as an Assembly site for Select Devices Customer Contact: PCN Manager Dept: Quality Services Proposed 1st Ship Date: Aug. 3, 2019 Estimated Sample Availability: Date provided at sample request Change Type: Image Type: Ima	PCN Number:	Number: 20190426000.1A				PCN Date: June 17, 2019			
Proposed 1 st Ship Date: Aug. 3, 2019 Estimated Sample Availability: Date provided at sample request Change Type:	Title: Qualific								
Proposed 1** Snp Date: Aug. 3, 2019 Availability: sample request Change Type:									
Assembly Site Design Wafer Bump Site Assembly Process Data Sheet Wafer Bump Process Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Site Wafer Fab Materials Packing/Shipping/Labeling Test Process Wafer Fab Materials Description of Change: Wafer Fab Process Wafer Fab Process PCN Details Description of Change: Wafer Fab Process Revision A is to announce the addition of new devices that were not included on the original PCN notification. These new devices are highlighted and bolded under Group 1 in the device light below. The expected first shipment date for these new devices will be 90 days from this notice (Sept 17, 2019) for these newly added devices only. The proposed 1 st ship date of Aug 3, 2019 still applies for the original set of devices. Texas Instruments is pleased to announce the qualification of TI Chengdu (CDAT) as an Additional Assembly site for the list of devices shown below. Current assembly sites and Material differences are as follows: Group 1 Device: Carsem Suzhou Carsem S CDAT Mount compound SID#455143 SID#435370 4222198 Group 2 Devices: Clark CDAT Moun	Proposed 1 st Ship Date: Aug. 3, 2019 Estimated Sample Date provi								
□ Assembly Process □ Data Sheet □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Mechanical Specification □ Test Site □ Wafer Fab Site □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ PCN Details □ Wafer Fab Materials □ Wafer Sab Materials □ Notification. These new devices are highlighted and bolded under Group 1 in the device list below. The expected first shipment date for these new devices will be 90 days from this notice □ Wafer Sab Material Sab Process. □ Texas Instruments is pleased to announce the qualification of TI Chengdu (CDAT) as an Addition	Change Type:								
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Material Declarationfrom production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below									
	following the								

Changes to product identification resulting from this PCN:						
Assembly Site Assembly Site Origin (22L) Assembly Country Code (21L) Assembly City						
TI Clark	QAB	PHL	Angeles City, Pampanga			
Carsem S	CRS	MYS	Jelapang			
Carsem Suzhou	CSZ	CHN	Jiangsu			

CDAT	CDA	CHN	Chengdu			
Sample product shipping label (not actual product label) TEXAS INSTRUMENTS MADE IN: Malaysia 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 (not actual product label) (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0:USA (22L) AS0: MLA (23L) AC0: MVS						
Product Affected:						
Group 1 Devices:						
SN0803054DRCR	SN75LVCP601RTJR	SN75LVCP601RTJT				
Group 2 Devices:		_				
TPS65233RTER	TPS65233RTET					

Group 1 Devices Qual Memo:

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Package Reference: BQ294504DRV	QBS Package Reference: TRS3122ERGE	QBS Package Reference: BQ24196RGE	QBS Package Reference: TPS51285BRUK	QBS Package Reference: TPS53641RSB
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	3/231/0	-	-	-
HTOL	Life Test, 150C	300 Hours	-	1/77/0	-	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	3/231/0
SD	Solderability	Pb Free	-	1/22/0	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
UHAST	Unbiased HAST, 110C/85%RH	264 Hours	-	-	-	-	-
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTSL options based on an activation energy of 0.7eV : 125C/1KHours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1KHours, and 170C/420 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1KHours, and 170C/420 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1KHours, and 170C/420 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1KHours, and 170C/420 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/150C/500 Cycles
Output and Environmental data is available at TTs external Web site: http://www.tl.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report (additional device) Approve Date 07-June-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>SN75LVCP601RTJR/</u> <u>T</u>	Qual Device: <u>HD3SS460RNH</u>	QBS Process Reference: <u>HD3SS3411TRWAQ1</u>			
AC	Autoclave 121C	96 Hours	1/77/0	1/77/0	3/231/0			
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass			
ELFR	Early Life Failure Rate, 140C	24 Hours	-	-	3/2400/0			
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0			
HBM	ESD - HBM	4000 V	-	1/3/0	1/3/0			
CDM	ESD - CDM	1500 V	-	1/3/0	1/3/0			
HTOL	Life Test, 140C	480 Hours	-	-	3/231/0			
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	2/90/0			
LU	Latch-up 90C	(per JESD78)	-	1/6/0	1/6/0			
LU	Latch-up 25C	(per JESD78)		1/6/0	1/6/0			
PD	Physical Dimensions	Cpk>1.67	1/5/0	3/15/0	3/30/0			
SD	Surface Mount Solderability	Pb Free	1/22/0	3/15/0	1/15/0			
SD	Surface Mount Solderability	Pb	1/22/0	3/15/0	1/15/0			
TC	Temperature Cycle, - 65/150C	500 Cycles	1/77/0	1/77/0	3/231/0			
MQ	Manufacturing Assembly	(per mfg. Site specification)	Pass	Pass	Pass			
BPC	Bond Pad Cratering Check			3/6/0				
TPI	Thermal Path Integrity	Level 2-260C(+5/-0C)		3/26/0	-			
UHAS T	Unbiased HAST, 130C/85%RH	96 Hours	-	3/231/0	-			
WBP	Bond Pull	Wires	1/76/0	3/228/0	3/228/0			
WBS	Ball Bond Shear	Wires	1/76/0	3/228/0	3/228/0			
VQR	Visual Quality Reliability Inspection	Post 500 Temp Cycle	1/2/0	1/2/0	-			

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL2-260C: HD3SS460IRNH, HD3SS460RNH

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "http://www.ti.com/lsds/ti/legal/termsofsale.page"

Group 2 Devices Qual Memo:

Туре	Test Name / Condition	Duration	Qual Device: TPS65233RTE	QBS Package Reference: <u>BQ24196RGER</u>	QBS Package Reference: <u>TPS54678RTE</u>
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-
ED	Electrical Characterization, side by side	-	Pass	-	Pass
HBM	ESD - HBM	4000 V	-	-	-
HBM	ESD - HBM	2000 V	-	-	-
CDM	ESD - CDM	1500 V	-	-	1/3/0
CDM	ESD - CDM	1000 V	-	-	-
CDM	ESD - CDM	750 V	-	-	-
LU	Latch-up	(per JESD78)	-	-	-
MM	ESD - MM	100 V	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-
HTSL	High Temp Storage Bake, 150C	1000 Hours	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-
AC	Autoclave 121C	96 Hours	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	-
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-
WBP	Bond Pull	Wires	-	3/228/0	-
WBS	Ball Bond Shear	Wires	-	3/228/0	-

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com